

Capability

3. Process & CPK value.
(Highlight all final finish are available).

1. CPK value of each Process

Process	Control Characteristic	CPK Value
Drilling	Hole Position Deviation/Hole Roughness	≥ 1.67 or According to customer's request
Pattern Plating	Copper thickness in hole	
Outer Etching	Line Width & Spacing / Impedance	
Solder Mask	Solder Mask Thickness	
Profiling	Outline Deviation(Routing)	
OSP	Coating Thickness	
IMAG (Immersion Silver)	Ag Thickness	
IMSN (Immersion Tin)	Tin Thickness	
ENIG(Immersion Gold)	Au Thickness	
Gold Finger Plating	Au Thickness	
Lead Free HASL	Surface Solder Thickness	
HASL	Surface Solder Thickness	

**All Process performed in-house, ensuring quality and availability.
No sub-contract work.**